



Material Content Data Sheet



Sales Product Name		SAK-XC2321D-20F66V AA		Issued		4. July 2019		
MA#		MA005348930						
Package		PG-VQFN-48-54		Weight*		126.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.350	4.23	4.23	42325	42325
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		140	
	non noble metal	zinc	7440-66-6	0.071	0.06		558	
	non noble metal	iron	7439-89-6	1.412	1.12		11168	
wire	non noble metal	copper	7440-50-8	57.319	45.35	46.54	453452	465318
	noble metal	gold	7440-57-5	0.733	0.58	0.58	5802	5802
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.14		1359
plastics		epoxy resin	-	7.271	5.75		57522	
	inorganic material	silicondioxide	60676-86-0	49.810	39.40	45.29	394048	452929
leadfinish	non noble metal	tin	7440-31-5	2.340	1.85	1.85	18515	18515
plating	noble metal	silver	7440-22-4	0.656	0.52	0.52	5189	5189
glue	plastics	epoxy resin	-	0.288	0.23		2282	
	noble metal	silver	7440-22-4	0.966	0.76	0.99	7640	9922
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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